



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

Notification# 20190402000.0
Datasheet for ADS8866
Information Only

Date: April 22, 2019
To: Newark/Farnell PCN

Dear Customer:

This is an information-only announcement of a change to the datasheet for a device that is currently offered by Texas Instruments.

The changes discussed within this notification are for your information only.

Any negotiated alternative change requirements will be provided via the customer's defined process. Customers with previously negotiated, special requirements will be handled separately. Any inquiries should be directed to your local Field Sales Representative.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Team (PCN_ww_admin_team@list.ti.com).

Sincerely,

PCN Team
SC Business Services



Information Only Attachments

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
ADS8866IDGS	null

Technical details of this Product Change follow on the next page(s).

PCN Number:	20190402000.0	PCN Date:	April 22, 2019
Title:	Datasheet for ADS8866		
Customer Contact:	PCN Manager	Dept:	Quality Services
Change Type:			
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design
<input type="checkbox"/>	Assembly Process	<input checked="" type="checkbox"/>	Data Sheet
<input type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site
<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Site
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Material
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Process
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Site
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Materials
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Process
Notification Details			
Description of Change:			
<p>Texas Instruments Incorporated is announcing an information only notification. The product datasheet(s) is being updated as summarized below. The following change history provides further details.</p>			
		ADS8866 <small>SBAS614C –MAY 2013–REVISED MARCH 2019</small>	
Changes from Revision B (February 2019) to Revision C			
			Page
•	Added <i>Input current</i> row to <i>Absolute Maximum Ratings</i> table		5
•	Changed Minimum f_{SCLK} required to achieve rated throughput.....		8
•	Changed Maximum t_{SCLK} to achieve rated throughput table.....		8
		ADS8866 <small>SBAS614B –MAY 2013–REVISED FEBRUARY 2019</small>	
Changes from Revision A (December 2013) to Revision B			
			Page
•	Added <i>Device Information</i> table, <i>ESD Ratings</i> table, <i>Recommended Operating Conditions</i> table, <i>Parametric Measurement Information</i> section, <i>Feature Description</i> section, <i>Device Functional Modes</i> section, <i>Application and Implementation</i> section, <i>Power Supply Recommendations</i> section, <i>Layout</i> section, <i>Device and Documentation Support</i> section, and <i>Mechanical, Packaging, and Orderable Information</i> section.....		1
•	Changed analog input from <i>pseudo-differential</i> to <i>single-ended</i> throughout document.....		1
•	Changed MSOP to VSSOP throughout document		1
•	Changed title of <i>Device Comparison Table</i> from <i>Family Information</i>		4
•	Changed footnotes of <i>Family Information</i> table.....		4
•	Changed LSB footnote in <i>Electrical Characteristics</i> table to include how to convert LSB to ppm		6
•	Added more information about validity of data on SCLK edges in all interface modes		21
•	Changed diagrams and text for better explanation of the daisy-chain feature in the <i>Daisy-Chain Mode</i> section		23
•	Changed Equation 1 and Equation 2		26
•	Changed <i>Charge-Kickback Filter</i> section title and functionality description		27
The datasheet number will be changing.			
Device Family	Change From:	Change To:	
ADS8866	SBAS614A	SBAS614B	
These changes may be reviewed at the datasheet links provided.			
http://www.ti.com/product/ADS8866			
Reason for Change:			
To accurately reflect device characteristics.			
Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):			
No anticipated impact. This is a specification change announcement only. There are no changes to the actual device.			
Changes to product identification resulting from this PCN:			

None.

Product Affected:

ADS8866IDGS	ADS8866IDGSR	ADS8866IDRCR	ADS8866IDRCT
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For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
WW PCN Team	PCN_ww_admin_team@list.ti.com